

## **Technical Data Sheet**

MODEL NO: 192UR/ANG4-JH 0603Package 1.6\*0.8\*0.6mm Chip LEDs

### Features:

- Package in 8mm tape on 7" diameter reel
- Compatible with automatic placement equipment
- Compatible with reflow solder process

### Applications:

- Indicators
- Automotive: backlighting in dashboard and switch
- Backlight for LCD

Dice material	Emitted color	Lens Color		
AlGaInP	Red			
		Water Clear		
InGaN/GaN	Green			

## Electrical/Optical Characteristics(Ta=25°C)

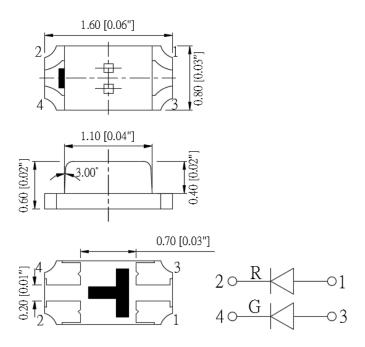
Parameter	Test	Cumbal		Value			l lmit
	Condition	Symbol		Min	Тур	Max	Unit
Spectral half bandwidth	IF=20mA	Δλ	R		20		- nm
			G		25		
Dominant wavelength	IF=20mA	λD	R	620		630	- nm
Dominant wavelength			G	520		530	
Forward voltage	IF=20mA	VF	R	1.8	2.0	2.4	V
			G	2.8	3.0	3.7	
Luminous intensity	IF=20mA	lv	R	80	140	200	mcd
			G	320	560	800	
Viewing angle at 50% Iv	IF=10mA	2 <i>0</i> 1/2	-	-	120	ı	Deg
Reverse current	V <sub>R</sub> =5V	lr	1	-	ı	10	μΑ

## Absolute Maximum Ratings(Ta= $25^{\circ}$ C)

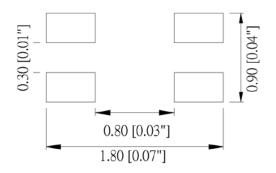
Parameter	Symbol		Value	Unit
Douge discination	Pd	R	72	mW
Power dissipation		G	111	
Forward current	lF		30	mA
Reverse voltage	Vr		5	V
Operating temperature range	Тор		-40 ~+80	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg		-40 ~+85	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/8 duty f=1kHz)	IFP		125	mA



# PACKAGING DIMENSIONS (mm):



### **RECOMMEND PAD LAYOUT**



### Notes:

- 1. All dimensions are in millimeters (inches);
- 2. Tolerances are  $\pm 0.1$ mm (0.004inch) unless otherwise noted.

### **Precautions For Use:**

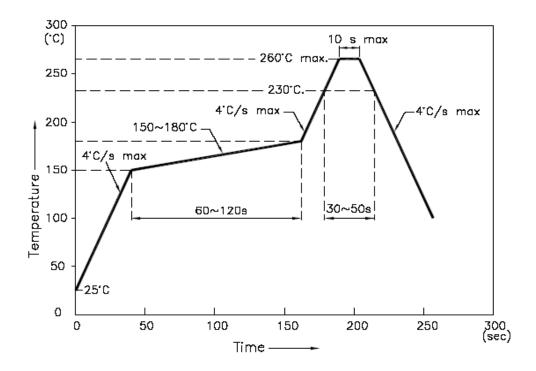
### Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

### Storage

- 1. The operation of temperature and R.H. are :  $5^{\circ}$ C  $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}\text{C}\pm5^{\circ}\text{C}$  for 15hrs.

### ■ Reflow Temp/Time



#### NOTES:

- 1. We recommend the reflow temperature  $245\,^{\circ}\text{C}(\pm 5\,^{\circ}\text{C})$ .the maximum soldering temperature should be limited to  $260\,^{\circ}\text{C}$ .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

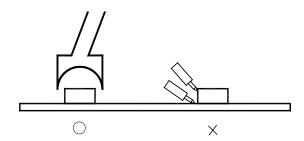


### ■Soldering iron

Basic spec is  $\leq$  5sec when 260°C. If temperature is higher, time should be shorter (+10°C  $\rightarrow$  -1sec ). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

### **■**Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \ solder etc.